



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4253E		<b>Issued</b>		26. September 2017		
<b>MA#</b>		MA000970042						
<b>Package</b>		PG-DSO-8-27		<b>Weight*</b>		84.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.234	2.65	2.65	26498	26498
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.728	0.86		8633	
wire	non noble metal	copper	7440-50-8	29.548	35.05	35.96	350524	359697
	noble metal	gold	7440-57-5	0.107	0.13	0.13	1264	1264
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1160
encapsulation	plastics	epoxy resin	-	4.498	5.34		53365	
	inorganic material	silicondioxide	60676-86-0	44.300	52.56	58.02	525534	580059
leadfinish	non noble metal	tin	7440-31-5	0.695	0.82	0.82	8246	8246
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8595	8595
glue	plastics	epoxy resin	-	0.330	0.39		3910	
	noble metal	silver	7440-22-4	0.989	1.17	1.56	11731	15641
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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